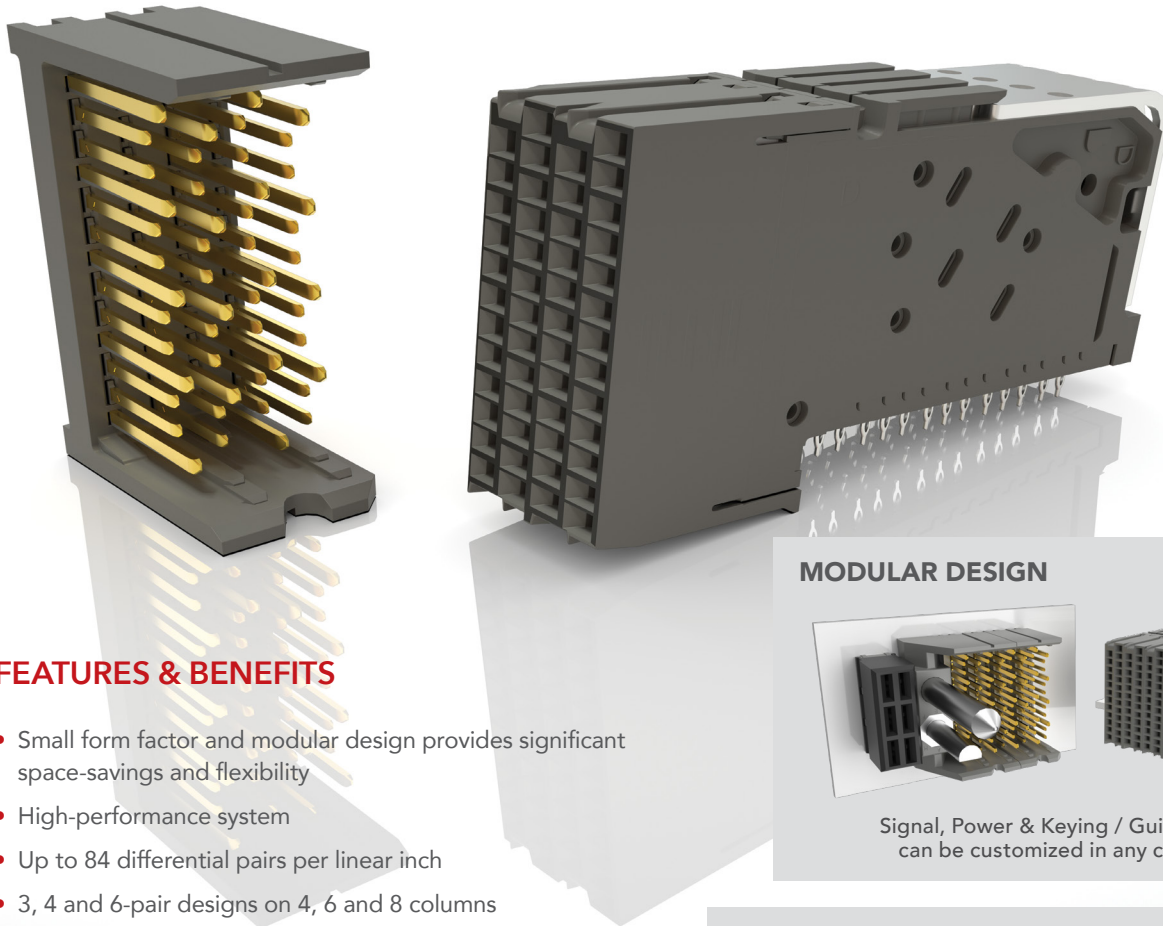


## HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

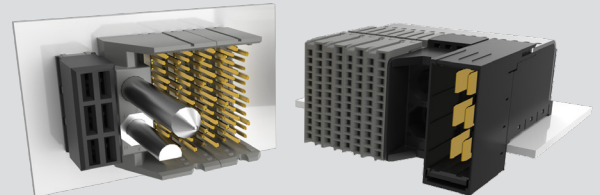
16  
G b p s



### FEATURES & BENEFITS

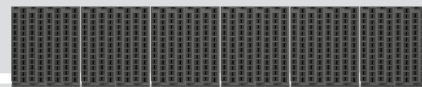
- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and side walls available
- 85  $\Omega$  and 100  $\Omega$  options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane. Visit [samtec.com?BSP](http://samtec.com?BSP) or contact [HSBP@samtec.com](mailto:HSBP@samtec.com)
- Press-fit extraction and insertion tool options; please visit [samtec.com/tooling](http://samtec.com/tooling) for details

### MODULAR DESIGN



Signal, Power & Keying / Guidance options can be customized in any configuration

### HIGH-DENSITY, SMALL FORM FACTOR



**XCede® HD**  
Up to 84 pairs per linear inch



**Traditional Backplane**  
Up to 76 pairs per linear inch

(Both shown with six 4-pair, 8 column receptacles)

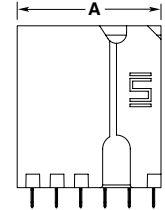
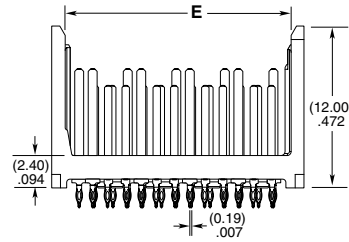
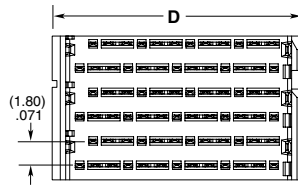
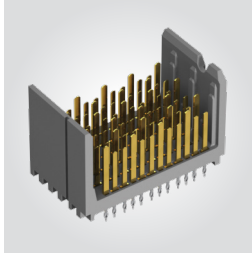
### KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
HDTM/HDTF	LCP	Phosphor Bronze (HDTM) Copper Alloy (HDTF)	Au or Sn over 50 $\mu$ " (1.27 $\mu$ m) Ni	-40 °C to + 105 °C	1.5 A per contact	48 VAC/ /68 VDC
HPTS/HPTT	LCP	Copper Alloy	Au or Sn over 50 $\mu$ " (1.27 $\mu$ m) Ni	-40 °C to + 105 °C	10 A per blade	48 VAC/ /68 VDC

# (1.80 mm) .071" PITCH • HIGH-DENSITY BACKPLANE HEADER

HDTM	PAIRS	NO. OF COLUMNS	TAIL SIZE	S	VT	SIDE WALLS	GUIDANCE	STAGE COMBO	KEYING
	-3, -4, -6 =Pairs Per Column	-04, -06, -08	-1 =(.4495 mm) .0177" Drill  -2 =(.5511 mm) .0217" Drill			-0 = Open (No Walls)  -1 = Left  -2 = Right  -4 = Left Polarizing with left guidance (-4 Pairs N/A)  -5 = Right Polarizing with right guidance (-4 Pairs N/A)	-4 or -5 Polarizing Only; Leave Blank for No Guidance  -L = Left Side Guide Pin (-4 Pairs N/A)  -R = Right Side Guide Pin (-4 Pairs N/A)	-1 = 3 mm Wipe Signal / 4 mm Wipe Ground  -2 = 2 mm Wipe Signal / 4 mm Wipe Ground  -3 = 3 mm Wipe Signal / 3 mm Wipe Ground  -4 = 2 mm Wipe Signal / 3 mm Wipe Ground  -5 = 2 mm Wipe Signal / 2 mm Wipe Ground	-4 or -5 Polarizing Only; Leave Blank for No Keying  -A thru -H = Position of Flat on Key (See Table)

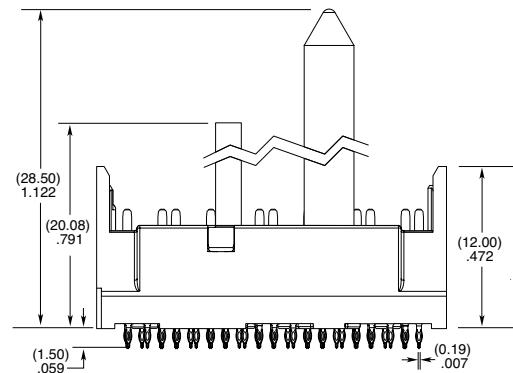
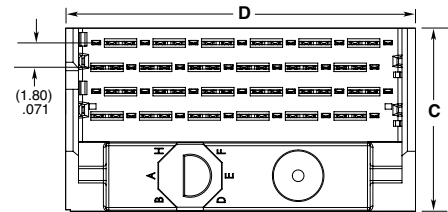
**HDTM**  
Board Mates:  
HDTF, BSP



**HDTM-4-06-1-S-VT-0-1 SHOWN**

NO. OF COLUMNS	A			C	
	No Walls	Left Wall	Right Wall	Left Polarize	Right Polarize
-04	(7.06) .278	(8.20) .323	(8.06) .317	N/A	N/A
-06	(10.66) .420	(11.80) .465	(11.66) .459	(17.14) .675	(16.65) .656
-08	(14.26) .561	(15.40) .606	(15.26) .600	(20.74) .817	(20.25) .797

PAIRS PER COLUMN	D	E
	Standard Wall	
-03	(15.10) .594	(13.15) .518
-04	(18.70) .736	(16.75) .659
-06	(25.90) 1.020	(23.95) .943



**HDTM-6-04-X-X-VT-4-L-X-A SHOWN**

## KEYING

-L / -R	-A	-B	-C	-D	-E	-F	-G	-H

### Notes:

Some lengths, styles and options are non-standard, non-returnable.

XCede® is a registered trademark of Amphenol.

View complete specifications at: [samtec.com?HDTM](http://samtec.com?HDTM)